



SOT500-5

PLLMC, plastic leadless module carrier package; 35 mm wide tape

5 October 2017

Package information

1. Package summary

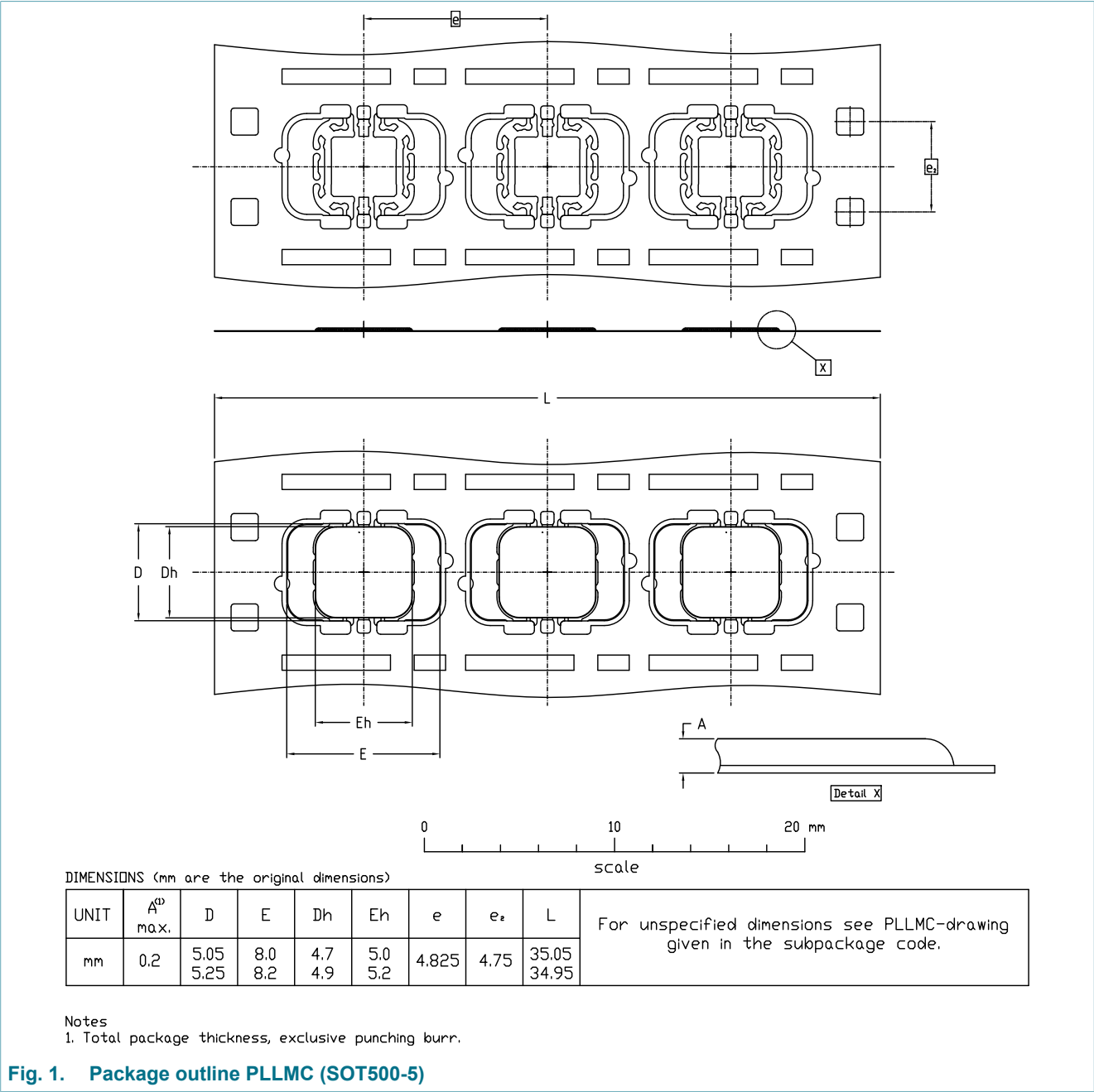
Terminal position code	B (bottom)
Package type descriptive code	PLLMC
Package type industry code	PLLMC
Package style descriptive code	PLLMC (plastic leadless module carrier)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	17-8-2017
Manufacturer package code	SOT500

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.05	-	5.1	5.25	mm
E	package width		34.95	-	35	35.05	m
A	seated height		-	-	-	0.2	mm
n ₂	actual quantity of termination		-	-	6	-	A/A



2. Package outline



3. Legal information

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